



Insulated Gate Bipolar Transistors IGBT-Chips

	Type	V_{CES}	$V_{DS(AMS)}$	@ I_C	C_{iss} typ	t_r typ	Chip type 25°C	Chip size dimensions		Source bond wire recommended	Equivalent device data sheet	Dim. out- line No.
	$T_{jst} = 150^\circ\text{C}$	V	V	A	pF	ns		mm	mils			
Low $V_{CE(sat)}$	IXGD28N30-43 IXGD40N30-5X	300	2.1 1.5	20 20	1500 2500	120 220	IX43 IX5X	5.64 x 4.67 6.58 x 6.58	222 x 184 259 x 259	15 mil x 1 15 mil x 2	IXGH28N30A IXGH40N30	1 25
	IXGD12N60B-33 IXGD31N60-4X IXGD41N60-5X IXGD60N60-7X IXGD200N60-9X	600	2.3 1.8 1.4 1.6 2.0	12 20 20 20 20	750 1500 2500 4000 9000	600 800 120 360 350	IX33 IX4X IX5X IX7X IX9X	4.39 x 3.60 5.65 x 4.70 6.59 x 6.59 8.84 x 7.18 14.20 x 10.60	173 x 142 222 x 185 259 x 259 348 x 283 559 x 417	12 mil x 1 15 mil x 1 15 mil x 2 15 mil x 3 15 mil x 6	IXGP12N60B IXGH31N60 IXGH41N60 IXGH60N60 IXGN200N60	3 28 26 29 23
	IXGD8N100-2L IXGD12N100-33 IXGD17N100-4T IXGD25N100-5T	1000	2.7 3.5 3.5 3.4	8 12 17 20	500 750 1500 2750	500 800 750 800	IX2L IX33 IX4T IX5T	3.68 x 3.42 4.39 x 3.60 5.77 x 4.96 6.73 x 6.61	125 x 125 173 x 142 227 x 195 265 x 260	12 mil x 1 12 mil x 1 15 mil x 1 10 mil x 4	IXGP8N100 IXGH12N100 IXGH17N100 IXGH25N100	31 3 7 8
	IXGD25N120-5T	1200	2.9	20	2750	800	IX5T	6.73 x 6.61	265 x 260	10 mil x 4	IXGH25N120	8
	IXGD28N30A-43 IXGD40N30A-5X	300	2.1 1.8	20 20	1500 2500	120 120	IX43 IX5X	5.64 x 4.67 6.58 x 6.58	222 x 184 259 x 259	15 mil x 1 20 mil x 1	IXGH28N30A IXGH40N30A	1 26
	IXGD22N50B-43 IXGD24N50B-43	500	2.5 2.3	20 20	1450 1500	80 120	IX43 IX43	5.64 x 4.67 5.64 x 4.67	222 x 184 222 x 184	15 mil x 1 15mil x 1	IXGH22N50B IXGH24N50B	1 1
	IXGD7N60B-2U IXGD20N60A-43 IXGD20N60B-4X IXGD24N60A-43 IXGD24N60B-4X IXGD28N60B-4X IXGD30N60B-5X IXGD32N60A-57 IXGD32N60B-5X IXGD50N60A-77 IXGD50N60B-7X IXGD200N60A-9X	600	1.8 3.0 2.0 2.7 2.5 2.0 1.6 2.7 2.3 2.7 2.2 2.2	7 20 20 20 20 20 20 20 20 20 20 20	500 1500 1500 1500 1500 1500 2500 2500 2500 4000 4000 9000	150 200 150 150 120 200 190 125 120 275 180 200	IX2U IX43 IX4X IX43 IX4X IX4X IX5X IX57 IX5X IX77 IX7X IX9X	3.68 x 3.42 5.64 x 4.67 5.65 x 4.70 5.64 x 4.67 5.65 x 4.70 5.65 x 4.70 6.58 x 6.58 6.58 x 6.58 6.59 x 6.59 8.84 x 7.19 8.84 x 7.18 14.20 x 10.6	145 x 135 222 x 184 222 x 185 222 x 184 222 x 185 222 x 185 259 x 259 259 x 259 259 x 259 348 x 283 348 x 283 559 x 417	12 mil x 1 15 mil x 1 15mil x 1 15 mil x 1 15mil x 1 15mil x 1 15 mil x 2 20 mil x 1 15 mil x 2 15 mil x 3* 15 mil x 3 15 mil x 6	IXGP7N60B IXGH20N60A IXGH20N60B IXGH24N60A IXGH24N60B IXGH28N60B IXGH30N60B IXGH32N60A IXGH32N60B IXGH50N60A IXGH50N60B IXGN200N60A	27 1 28 1 28 28 26 2 21 4 29 23
	IXGD12N100A-33 IXGD17N100A-4T IXGD25N100A-5T	1000	4.0 4.0 3.9	12 17 20	750 1500 2750	500 450 500	IX33 IX4T IX5T	4.39 x 3.60 5.77 x 4.96 6.73 x 6.61	173 x 142 227 x 195 265 x 260	12 mil x 1 15 mil x 1 10 mil x 4	IXGH12N100A IXGH17N100A IXGH25N100A	3 7 8
	IXGD25N120A-5T	1200	3.9	20	2750	600	IX5T	6.73 x 6.61	265 x 260	10 mil x 4	IXGH25N120A	8

Notes:

- Recommended Gate bond wire is 8 mil except 6 mil wire must be used for * types.
- Maximum switching limits from packaged device data sheet are not guaranteed.
Dice type with B suffix letter: To guarantee switching speeds:
- Element evaluation sample to be built from each lot to test V_{sat} and switching speeds at full current.
- Every order will be accompanied by a lot charge for element evaluation
- Dice are tested to V_{sat} limits as indicated up to a maximum of $I_c = 20$ A max.
- Recommended die processing thermal budget is not to exceed 365 degC for 5 minutes.

IXYS reserves the right to change limits, test conditions and dimensions.